

DTMF Generators

Features

- Operating voltage: 2.0V~5.5V
- Serial mode for the HG9200A
- Serial/parallel mode for the HG9200B
- Low standby current
- Low total harmonic distortion
- 3.58MHz crystal or ceramic resonator
- HG9200A: 8-pin DIP/SOP package
- HG9200B: 14-pin SOP package



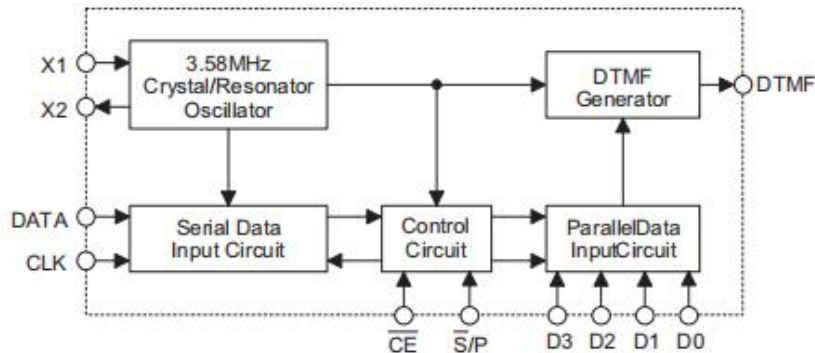
Ordering Information

DEVICE	Package Type	MARKING	Packing	Packing Qty
HG9200AN	DIP-8	HG9200A	TUBE	2000pcs/box
HG9200AM/TR	SOP-8	HG9200A	REEL	2500pcs/reel
HG9200BM/TR	SOP-14	HG9200B	REEL	2500pcs/reel

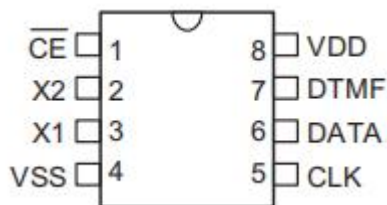
General Description

The HG9200A/B tone generators are designed for MCU interfaces. They can be instructed by a MCU to generate 16 dual tones and 8 single tones from the DTMF pin. The HG9200A provides a serial mode whereas the HG9200B contains a selectable serial/parallel mode interface for various applications such as security systems, home automation, remote control through telephone lines, communication systems, etc.

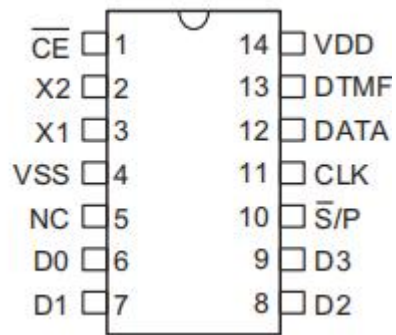
Block Diagram



Pin Assignment



HG9200A
DIP-8/SOP-8



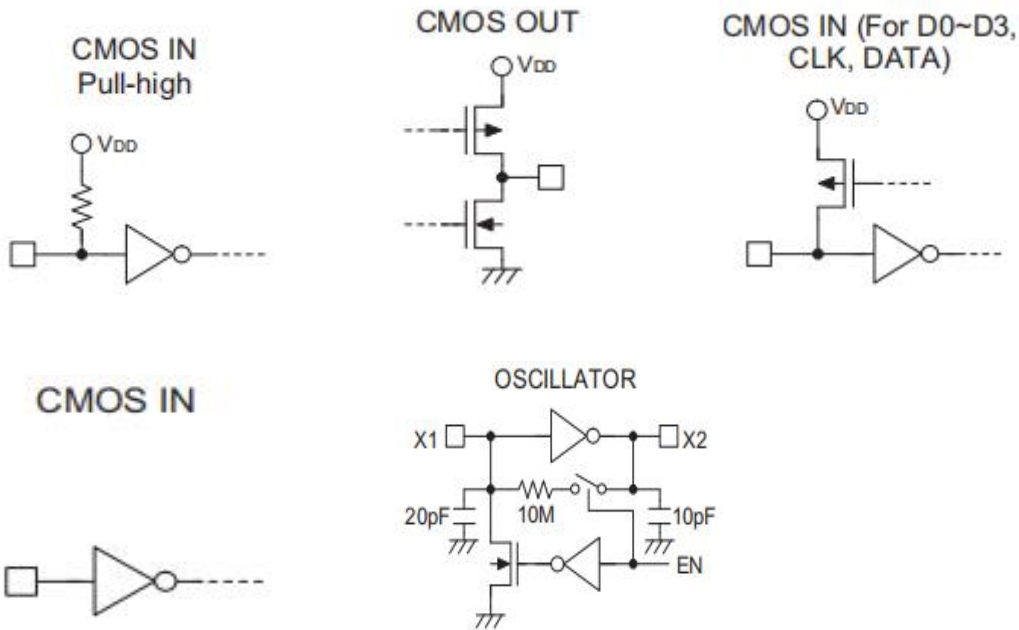
HG9200B
SOP-14

Pin Description

Pin Name	I/O	Internal Connection	Description
\overline{CE}	I	CMOS IN Pull-high	Chip enable, active low
X2	O	Oscillator	The system oscillator consists of an inverter, a bias resistor, and the required load capacitor on chip. The oscillator function can be implemented by Connect a standard 3.579545MHz crystal to the X1 and X2 terminals.
X1	I		
VSS			Negative power suppl, ground
NC			No connection
D0~D3	I	CMOS IN Pull-high or Floating	Data inputs for the parallel mode When the IC is operating in the serial mode, the data input terminals (D0~D3) are included with a pull-high resistor. When the IC is operating in the parallel mode, these pins become floating.
$\overline{S/P}$	I	CMOS IN	Operation mode selection input $\overline{S/P}$ ="H": Parallel mode $\overline{S/P}$ ="L": Serial mode
CLK	I	CMOS IN Pull-high or Floating	Data synchronous clock input for the serial mode When the IC is operating in the parallel mode, the input terminal (CLK) is included with a pull-high resistor. When the IC is operating in the serial mode, this pin becomes floating.

Pin Name	I/O	Internal Connection	Description
DATA	I	CMOS IN Pull-high or Floating	Data input terminal for the serial mode When the IC is operating in the parallel mode, the input terminal (DATA) is included with a pull-high resistor. When the IC is operating in the serial mode, this pin becomes floating.
DTMF	O	CMOS OUT	Output terminal of the DTMF signal
VDD			Positive power supply, 2.0V~5.5V for normal operation

Approximate internal connection circuits



Absolute Maximum Ratings

Condition	Min	Max	UNITS
Supply Voltage	-0.3	6	V
Input Voltage	VSS-0.3	VDD+0.3	V
Storage Temperature	-50	125	°C
Operating Temperature	-20	75	°C
Lead Temperature (Soldering, 10 seconds)	-	245	°C

Note: These are stress ratings only. Stresses exceeding the range specified under Absolute Maximum Ratings may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Electrical Characteristics

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		VDD	Conditions				
V _{DD}	Operating Voltage	-	-	2	-	5.5	V
I _{DD}	Operating Current	2.5V	$\bar{S}/P=V_{DD}, D0\sim D3=V_{SS},$	-	240	2500	μA
		5.0V	$\bar{CE}=V_{SS},$ No load	-	950	3000	
V _{IL}	“Low” Input Voltage	-	-	V _{SS}	-	0.2V _{DD}	V
V _{IH}	“High” Input Voltage	-	-	0.8V _{DD}	-	V _{DD}	V
I _{STB}	Standby Current	2.5V	$\bar{S}/P=V_{DD}, \bar{CE}=V_{DD},$ no load	-	-	1	μA
		5.0V		-	-	2	
R _P	Pull-high Resistance	2.5V	VOL=0V	120	180	270	kΩ
		5.0V		45	68	100	
t _{DE}	DTMF Output Delay Time (Parallel Mode)	5V	-	-	t _{UP} +6	t _{UP} +8	ms
V _{TDC}	DTMF Output DC Level	2V~ 5.5V	DTMF Output	0.45V _{DD}	-	0.75V _{DD}	V
I _{TOL}	DTMF Sink Current	2.5V	V _{DTMF} =0.5V	0.1			mA
V _{TAC}	DTMF Output AC Level	2.5V	Row group, RL=5kΩ	0.12	0.15	0.18	V _{rms}
A _{CR}	Column Pre-emphasis	2.5V	Row group=0dB	1	2	3	dB
R _L	DTMF Output Load	2.5V	t _{HD} ≤ -23dB	5	-	-	kΩ
t _{HD}	Tone Signal Distortion	2.5V	RL=5kΩ	-	30	23	dB
f _{CLK}	Clock Input Rate (Serial Mode)	-	-	-	100	500	kHz
t _{UP}	Oscillator Starting Time (When \bar{CE} is low)	5.0V	The time from \bar{CE} falling edge to normal oscillator operation	-	-	10	ms
f _{OSC}	System Frequency	-	Crystal=3.5795MHz	3.5759	3.5795	3.5831	MHz

Functional Description

The HG9200A/B are DTMF generators for MCU interfaces. They are controlled by a MCU in the serial mode or the parallel mode (for the HG9200B only).

Serial mode (HG9200A/B)

The HG9200A/B employ a data input, a 5-bit code, and a synchronous clock to transmit a DTMF signal. Every digit of a phone number to be transmitted is selected by a series of inputs which consist of 5-bit data. Of the 5 bits, the D0(LSB) is the first received bit. The HG9200A/B will latch data on the falling edge of the clock (CLK pin). The relationship between the digital codes and the tone output frequency is shown in Table 1. As for the control timing diagram, refer to Figure 1.

When the system is operating in the serial mode a pull-high resistor is attached to D0~D3 (for parallel mode) on the input terminal.

Table 1: Digits vs. input data vs. tone output frequency (serial mode)

Digit	D4	D3	D2	D1	D0	Tone Output Frequency (Hz)
1	0	0	0	0	1	697+1209
2	0	0	0	1	0	697+1336
3	0	0	0	1	1	697+1477
4	0	0	1	0	0	770+1209
5	0	0	1	0	1	770+1336
6	0	0	1	1	0	770+1477
7	0	0	1	1	1	852+1209
8	0	1	0	0	0	852+1336
9	0	1	0	0	1	852+1477
0	0	1	0	1	0	941+1336
*	0	1	0	1	1	941+1209
#	0	1	1	0	0	941+1477
A	0	1	1	0	1	697+1633
B	0	1	1	1	0	770+1633
C	0	1	1	1	1	852+1633
D	0	0	0	0	0	941+1633
-	1	0	0	0	0	697
-	1	0	0	0	1	770
-	1	0	0	1	0	852
-	1	0	0	1	1	941
-	1	0	1	0	0	1209
-	1	0	1	0	1	1336
-	1	0	1	1	0	1477
-	1	0	1	1	1	1633
DTMF OFF	1	1	1	1	1	-

Note: The codes not listed in Table 1 are not used D4 is MSB

For the HG9200B, the \bar{S}/P pin has to be connected low for serial mode operation.

Parallel mode (HG9200B)

The HG9200B provides four data inputs D0~D3 to generate their corresponding DTMF signals. The \bar{S}/P has to be connected high to select the parallel operation mode. Then the input data codes should be determined. Finally, the \bar{CE} is connected low to transmit the DTMF signal from the DTMF pin.

The TDE time (about 6ms) will be delayed from the \bar{CE} falling edge to the DTMF signal output.

The relationship between the digital codes and the tone output frequency is illustrated in Table 2. As for the control timing diagram, see Figure 2. When the system is operating in the parallel mode, D0~D3 are all in the floating state. Thus, these data input pins should not float.

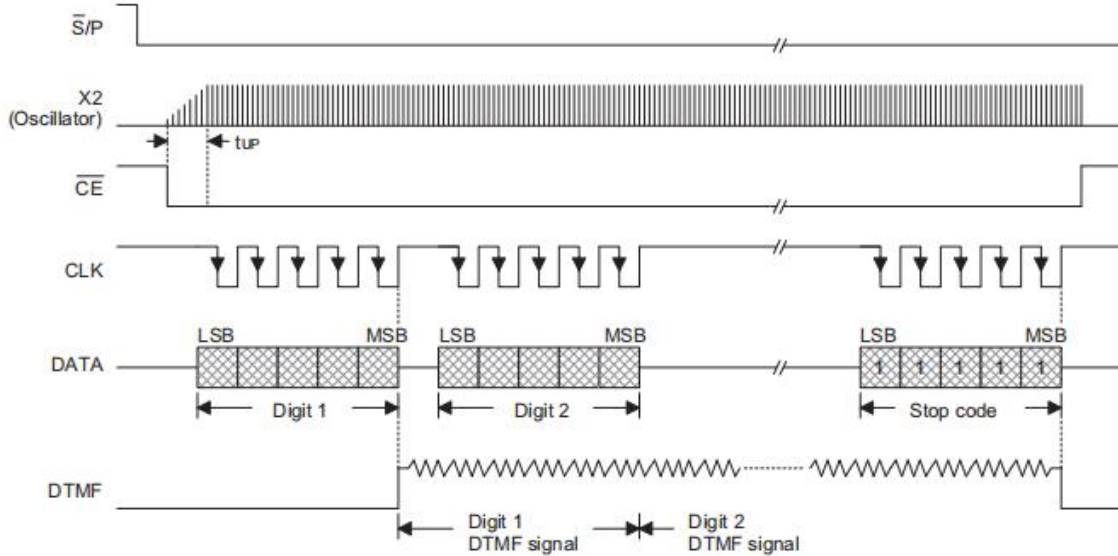
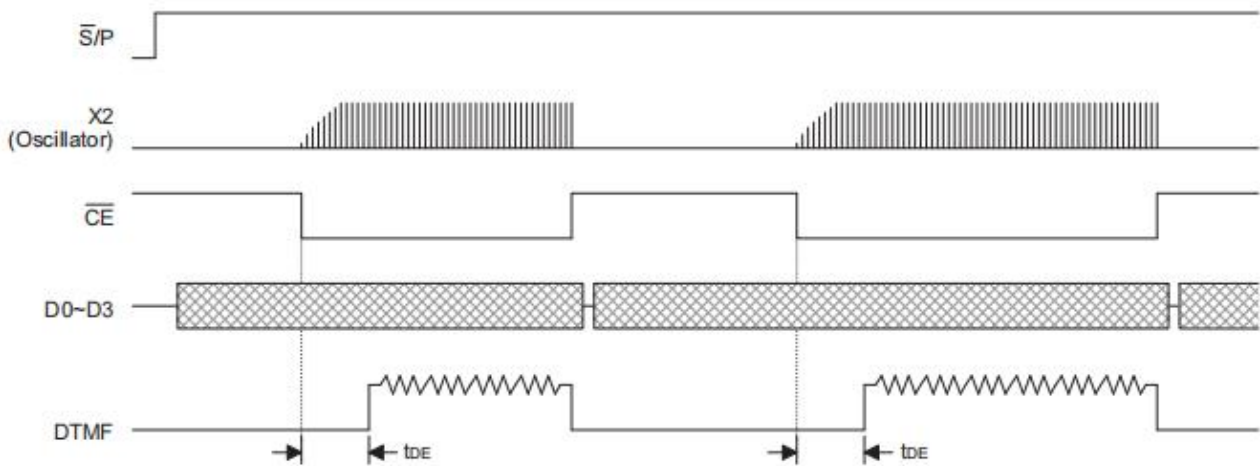


Figure 1

Table 2: Digits vs. input data vs. tone output frequency (parallel mode)

Digit	D3	D2	D1	D0	Tone Output Frequency (Hz)
1	0	0	0	1	697+1209
2	0	0	1	0	697+1336
3	0	0	1	1	697+1477
4	0	1	0	0	770+1209
5	0	1	0	1	770+1336
6	0	1	1	0	770+1477
7	0	1	1	1	852+1209
8	1	0	0	0	852+1336
9	1	0	0	1	852+1477
0	1	0	1	0	941+1336
*	1	0	1	1	941+1209
#	1	1	0	0	941+1477
A	1	1	0	1	697+1633
B	1	1	1	0	770+1633
C	1	1	1	1	852+1633
D	0	0	0	0	941+1633



Note: The data (D0~D3) should be ready before the \overline{CE} becomes low.

Figure 2

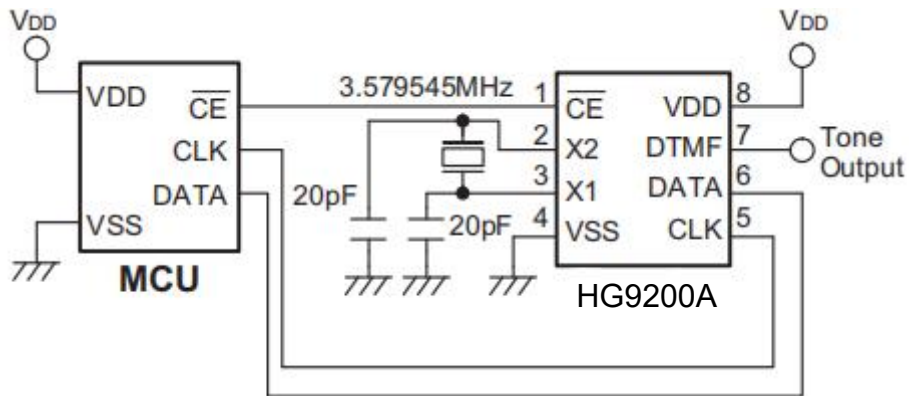
Tone frequency

Output Frequency (Hz)		%Error
Specified	Actual	
697	699	+0.29%
770	766	-0.52%
852	847	-0.59%
941	948	+0.74%
1209	1215	+0.50%
1336	1332	-0.30%
1477	1472	-0.34%

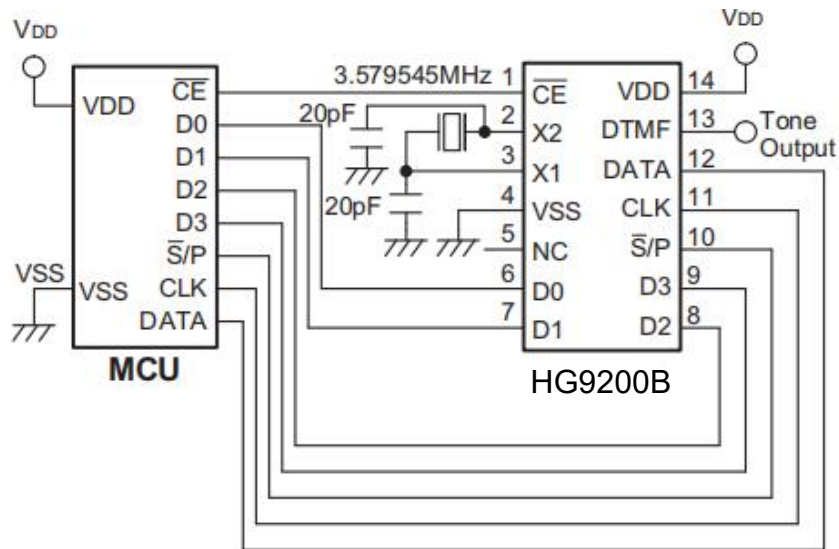
% Error does not contain the crystal frequency drift

Application Circuits

Serial mode

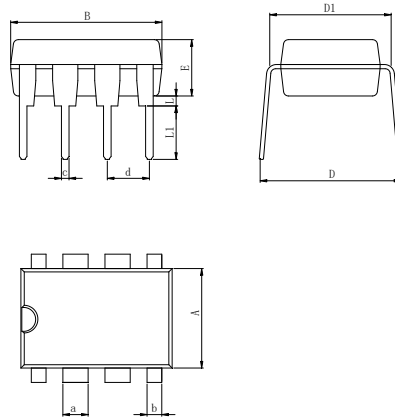


Serial/parallel mode



Physical Dimensions

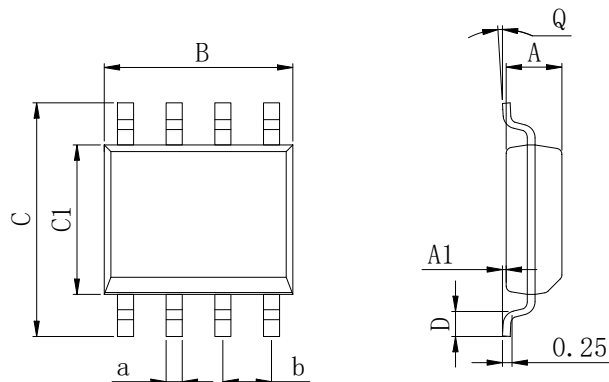
DIP-8



Dimensions In Millimeters(DIP-8)

Symbol:	A	B	D	D1	E	L	L1	a	b	c	d
Min:	6.10	9.00	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54 BSC
Max:	6.68	9.50	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	

SOP-8 (150mil)

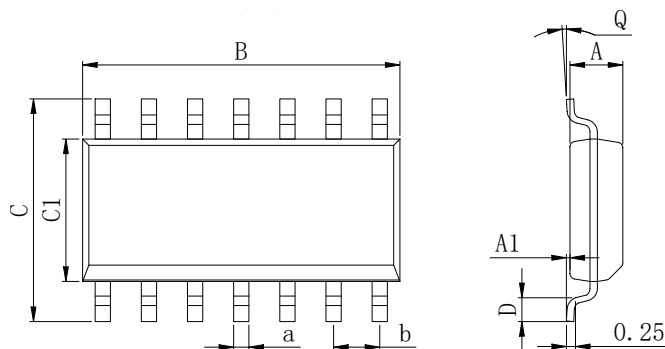


Dimensions In Millimeters(SOP-8)

Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	

Physical Dimensions

SOP-14



Dimensions In Millimeters(SOP-14)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	8.55	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	8.75	6.20	4.00	0.80	8°	0.45	

Revision History

DATE	REVISION	PAGE
2014-6-9	New	1-12
2023-8-30	Update encapsulation type、Update Lead Temperature、Updated DIP-8 dimension	1、 3、 9

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